# Gigabit Ethernet LAN Switch with 2:1 Mux/ DeMux and Power-down Feature

The NCN7200 is pin-compatible to the PI3L720ZHE and comes in a 42-pin WQFN package (3.5 mm x 9 mm x 0.5 mm Pitch). The NCN7200 is an 8-channel, bidirectional switch with a power shutdown feature that puts all outputs in a high-impedance state. The switch is compatible with 10/100/1000 Base-T Ethernet standards. The device has 3 additional lines for status indicator LEDs which are switched together with the Ethernet pairs.

#### **Features**

- 2:1 Mux/ DeMux LAN Switch
- Three Extra Channels Facilitate LED Switching
- Fully Specified for Power Supply Range: 3 V to 3.6 V
- Powerdown Feature Conserves Energy
- ESD Protection
  - 8 kV HBM (Human Body Model, I/O to GND)
  - ◆ 10 kV Contact Discharge (IEC61000-4-2)
- Low Crosstalk: -70 dB
- Pin-to-Pin Replacement for PI3L720ZHE
- This is a Pb-Free Device

### **Typical Applications**

- Routes signals for 10/100/1000 Mbps Ethernet
- Facilitates Docking System by Interfacing One Controller to Dual Connectors



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http://onsemi.com

#### MARKING DIAGRAM



NCN7200 AWLYYWWG

#### WQFN42 CASE 510AP

A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

E = Pb-Free Package

# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

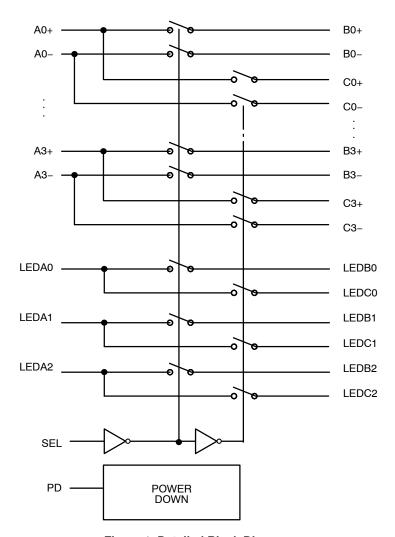


Figure 1. Detailed Block Diagram

# **TRUTH TABLE**

PD	SEL	Function	
L	L	AX to BX; LEDAX to LEDBX	
L	Н	AX to CX; LEDAX to LEDCX	
Н	Х	Hi–Z	

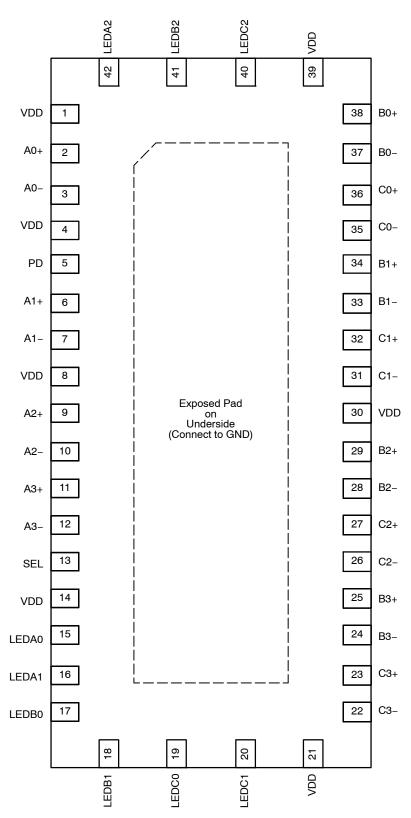


Figure 2. Pin Description (Top View)

#### **PIN DESCRIPTION**

Pin Name	Description
AX+, AX-	Port A DeMux I/O
BX+, BX-	Port B Mux I/O
CX+, CX-	Port C LED Mux I/O
GND	Ground
LEDZX	LED I/O
PD	Powerdown, Active high, with internal pulldown resistor
SEL	Select
V <sub>DD</sub>	Power

#### **MAXIMUM RATINGS**

Description	Value	Unit
Storage Temperature	-65 to +150	°C
Supply Voltage to Ground Potential	-0.5 to +4.0	V
DC Input Voltage	−0.5 to +5.5	V
DC Output Current (Note 1)	120	mA
Power Dissipation (Note 1)	0.5	W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### GIGABIT ETHERNET LAN SWITCH WITH 2:1 MUX/ DEMUX AND POWER DOWN FEATURE

(Min / Max values are at  $V_{DD}$  = 3.3 V  $\pm 10\%$ ,  $T_A$  =  $-40^{\circ}C$  to  $+85^{\circ}C$ . Typ values are at  $V_{DD}$  = 3.3 V and  $T_A$  =  $25^{\circ}C$ )

Symbol	Description	Test Conditions	Min	Тур	Max	Unit
CONTROL	LOGIC (SEL AND PD PINS) DC ELE	CTRICAL CHARACTERISTICS FOR 1000 B	ASE-T ETH	ERNET S	WITCHING	ì
V <sub>IH</sub>	Input HIGH Voltage	Guaranteed HIGH level	2.0			V
V <sub>IL</sub>	Input LOW Voltage	Guaranteed LOW level	-0.5		0.8	
V <sub>IK</sub>	Clamp Diode Voltage	$V_{DD} = Max$ , $I_{IN} = -18 \text{ mA}$		-0.7	-1.0	
I <sub>IHSEL</sub>	Input HIGH Current (SEL)	$V_{DD} = Max, V_{IN} = V_{DD}$			±0.1	μΑ
I <sub>IHPD</sub>	Input High Current (PD)	$V_{DD} = Max, V_{IN} = V_{DD}$			±1.2	
I <sub>IL</sub>	Input LOW Current	$V_{DD} = Max, V_{IN} = GND$			±0.1	
I <sub>OFF</sub>	Off-Leakage Current (SEL)	$V_{DD} = 0 \text{ V}, V_{IN} = 0 \text{ V to } V_{DD}$			±0.1	

- 2. Active power represents normal data communication. Standby power is when the device is enabled for operation but there is no LAN traffic (cable not connected). Power down current is the minimum power state used when not connected and mobile.
- 3. Measured by the voltage drop between A and B pins at indicated current through the switch. ON resistance is determined by the lower of the voltages on the two (A & B) pins.
- 4. Guaranteed by design and/or characterization.
- 5. The bus switch contributes no propagational delay other than the RC delay of the ON resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25 ns for 10 pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interactions with the load on the driven side.

Continuous short—circuit operation to ground at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C. Output currents in excess of 45 mA over long term may adversely affect reliability. Shorting output to either V+ or V- will adversely affect reliability.

#### GIGABIT ETHERNET LAN SWITCH WITH 2:1 MUX/ DEMUX AND POWER DOWN FEATURE

(Min / Max values are at  $V_{DD}$  = 3.3 V  $\pm 10\%$ ,  $T_A$  =  $-40^{\circ}C$  to  $+85^{\circ}C$ . Typ values are at  $V_{DD}$  = 3.3 V and  $T_A$  =  $25^{\circ}C$ )

Symbol	Description	Test Conditions	Min	Тур	Max	Unit
DATA PATH	I (AX TO BX, CX PINS) DC ELECTRI	CAL CHARACTERISTICS FOR 1000 BASE-T	ETHERNI	ET SWITC	HING	
R <sub>ON</sub>	Switch On-Resistance (Note 3)	$V_{DD} = Min, 1.5 V < V_{IN} < V_{DD}, I_{TN} = -40 \text{ mA}$		2.0	6.0	Ω
R <sub>FLAT(ON)</sub>	On-Resistance Flatness (Note 3)	$V_{DD}$ = Min, $V_{IN}$ @ 1.5 V and $V_{DD}$ , $I_{TN}$ = $-40$ mA		0.3		
$\Delta R_{ON}$	On–Resistance match from center ports to any other port (Note 3)	$V_{DD} = Min, 1.5 \text{ V} < V_{IN} < V_{DD}, I_{TN} = -40 \text{ mA}$		0.5	1.0	
I <sub>ON</sub>	On Leakage Current (AX)	$V_{DD} = 3.6 \text{ V}, V_{AX} = 0 \text{ V or } V_{DD}, V_{OUT} = \text{Float}$	-0.1		+0.1	μΑ
I <sub>OFF</sub>	Off Leakage Current (AX/BX/CX)	$V_{DD}$ = 3.6 V, $V_{IN}$ = 0 V or $V_{DD}$ , $V_{OUT}$ = $V_{DD}$ or 0 V	-0.1		+0.1	μΑ
DATA PATH SWITCHING		DC ELECTRICAL CHARACTERISTICS FOR 10	000 BASE	-T ETHE	RNET	
R <sub>ON</sub>	Switch On-Resistance (Note 3)	$V_{DD} = Min, 1.5 V < V_{IN} < V_{DD}, I_{TN} = -40 \text{ mA}$		7.0	16	Ω
R <sub>FLAT(ON)</sub>	On-Resistance Flatness (Note 3)	$V_{DD}$ = Min, $V_{IN}$ @ 1.5 V and $V_{DD}$ , $I_{TN}$ = $-40$ mA		0.3		
$\Delta R_{ON}$	On-Resistance match from center	$V_{DD} = Min, 1.5 \text{ V} < V_{IN} < V_{DD}, I_{TN} = -40 \text{ mA}$		0.8	1.25	

# CONTROL LOGIC (SEL AND PD PINS) DC ELECTRICAL CHARACTERISTICS FOR 10/100 BASE-T ETHERNET SWITCHING

 $V_{DD} = 3.6 \text{ V}, V_{AX} = 0 \text{ V or } V_{DD}, V_{OUT} = \text{Float}$ 

 $V_{DD}$  = 3.6 V,  $V_{IN}$  = 0 V or  $V_{DD}$ ,  $V_{OUT}$  =  $V_{DD}$  or 0 V

+0.1

μΑ

μΑ

$V_{IH}$	Input HIGH Voltage	Guaranteed HIGH level (Control Pins)	2.0			V
V <sub>IL</sub>	Input LOW Voltage	Guaranteed LOW level (Control Pins)	-0.5		8.0	
V <sub>IK</sub>	Clamp Diode Voltage	$V_{DD} = Max, IN = -18 \text{ mA}$		-0.7	-1.0	
I <sub>IHSEL</sub>	Input HIGH Current (SEL)	$V_{DD} = Max, V_{IN} = V_{DD}$			±0.1	μΑ
I <sub>IHPD</sub>	Input HIGH Current (PD)	$V_{DD} = Max, V_{IN} = V_{DD}$			±1.2	
I <sub>IL</sub>	Input LOW Current	$V_{DD} = Max, V_{IN} = GND$			±0.1	
I <sub>OFF</sub>	Off-Leakage Current (SEL)	$V_{DD} = 0 \text{ V}, V_{IN} = 0 \text{ V to } V_{DD}$			±0.1	

#### DATA PATH (AX TO BX, CX PINS) DC ELECTRICAL CHARACTERISTICS FOR 10/100 BASE-T ETHERNET SWITCHING

R <sub>ON</sub>	Switch On-Resistance (Note 3)	$V_{DD} = Min, 1.25 V < V_{IN} < V_{DD}, I_{TN} = -10 \text{ mA}$ to $-30 \text{ mA}$		2.0	6.0	Ω
R <sub>FLAT(ON)</sub>	On–Resistance Flatness (Note 3)	$V_{DD}$ = Min, 1.25 V < $V_{IN}$ < $V_{DD}$ , $I_{TN}$ = -10 mA to -30 mA		0.8		
$\Delta R_{ON}$	On–Resistance match from center ports to any other port (Note 3)	$V_{DD} = Min, 1.25 V < V_{IN} < V_{DD}, I_{TN} = -10 \text{ mA}$ to $-30 \text{ mA}$		0.8	1.3	
I <sub>ON</sub>	On Leakage Current (AX)	$V_{DD} = 3.6 \text{ V}, V_{AX} = 0 \text{ V or } V_{DD}, V_{OUT} = \text{Float}$	-0.1		+0.1	μА
l <sub>OFF</sub>	Off Leakage Current (AX/BX/CX)	$V_{DD}$ = 3.6 V, $V_{IN}$ = 0 V or $V_{DD}$ , $V_{OUT}$ = $V_{DD}$ or 0 V	-0.1		+0.1	μΑ

- 2. Active power represents normal data communication. Standby power is when the device is enabled for operation but there is no LAN traffic (cable not connected). Power down current is the minimum power state used when not connected and mobile.
- 3. Measured by the voltage drop between A and B pins at indicated current through the switch. ON resistance is determined by the lower of the voltages on the two (A & B) pins.
- 4. Guaranteed by design and/or characterization.

ports to any other port (Note 3)
On Leakage Current (LEDAX)

Off Leakage Current

(LEDAX/LEDBX/LEDCX)

 $I_{ON}$ 

**IOFF** 

5. The bus switch contributes no propagational delay other than the RC delay of the ON resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25 ns for 10 pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interactions with the load on the driven side.

#### GIGABIT ETHERNET LAN SWITCH WITH 2:1 MUX/ DEMUX AND POWER DOWN FEATURE

(Min / Max values are at  $V_{DD}$  = 3.3 V ±10%,  $T_A$  = -40°C to +85°C. Typ values are at  $V_{DD}$  = 3.3 V and  $T_A$  = 25°C)

Symbol	Description	Test Conditions	Min	Тур	Max	Unit
DATA PATH SWITCHING		DC ELECTRICAL CHARACTERISTICS FOR 10	D/100 BA	SE-T ETH	ERNET	
R <sub>ON</sub>	Switch On-Resistance (Note 3)	$V_{DD} = Min, 1.25 V < V_{IN} < V_{DD}, I_{TN} = -10 \text{ mA}$ to $-30 \text{ mA}$		7.0	16	Ω
R <sub>FLAT(ON)</sub>	On-Resistance Flatness (Note 3)	$V_{DD}$ = Min, 1.25 V < $V_{IN}$ < $V_{DD}$ , $I_{TN}$ = -10 mA to -30 mA		0.3		
$\Delta R_{ON}$	On–Resistance match from center ports to any other port (Note 3)	$V_{DD} = Min, 1.25 \text{ V} < V_{IN} < V_{DD}, I_{TN} = -10 \text{ mA}$ to $-30 \text{ mA}$		0.8	1.25	
I <sub>ON</sub>	On Leakage Current (LEDAX)	$V_{DD} = 3.6 \text{ V}, V_{AX} = 0 \text{ V or } V_{DD}, V_{OUT} = \text{Float}$	-0.1		+0.1	μΑ
I <sub>OFF</sub>	Off Leakage Current (LEDAX/LEDBX/LEDCX)	$V_{DD}$ = 3.6 V, $V_{IN}$ = 0 V or $V_{DD}$ , $V_{OUT}$ = $V_{DD}$ or 0 V	-0.1		+0.1	μΑ
CAPACITAN	NCE (AX TO BX, CX AND LEDAX TO	D LEDBX, LEDCX PINS) (Note 4)				
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0 V, f = 1 MHz		3.0	4.0	pF
C <sub>OFF(B1,</sub> B2)	Port B Capacitance, Switch OFF			5.0	7.0	
C <sub>ON(A/B)</sub>	A/B Capacitance, Switch ON			10.5	12	1
POWER SU	PPLY CHARACTERISTICS (Note 2)					-
I <sub>DD-Standby</sub>	Quiescent Power Supply Current	$V_{DD}$ = 3.6 V, $V_{IN}$ = GND or $V_{DD}$		0.38	0.45	mA
I <sub>DD-Active</sub>	Active Power Supply Current	$V_{DD}$ = 3.6 V, $V_{IN}$ = $V_{DD}$ or GND		1.0	1.5	mA
I <sub>DD-PD</sub>	Power Down Current	P <sub>D</sub> = 1, V <sub>DD</sub> = 3.6 V, V <sub>IN</sub> = V <sub>DD</sub> or GND		0.13	0.16	mA
DYNAMIC E	ELECTRICAL CHARACTERISTICS (	AX TO BX AND LEDAX TO LEDBX PINS) (Note	5)			
BW	Bandwidth -3 dB	$R_L$ = 100 $\Omega$ (Figure 3)		750		MHz
O <sub>IRR</sub>	OFF Isolation	$R_L$ = 100 $\Omega$ , f = 250 MHz (Figure 7)		-30		dB
XTALK	Crosstalk	$R_L$ = 100 $\Omega$ , f = 250 MHz (Figure 8)		-70		
SWITCHING	CHARACTERISTICS (AX TO BX A	ND LEDAX TO LEDBX PINS) (Notes 4 and 5)				
t <sub>PD</sub>	Propagation Delay (Figure 4)			0.3		ns
t <sub>PZH</sub> , t <sub>PZL</sub>	Line Enable Time - SEL to AN, BN	(Figure 4)	0.5		15	
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Line Disable Time - SEL to AN, BN	(Figure 4)	0.5		25	
t <sub>SK(o)</sub>	Output Skew between center port to	any other port		0.1	0.2	
t <sub>SK(p)</sub>	Skew between opposite transitions	of the same output (t <sub>Hil</sub> , - t <sub>PLH</sub> )		0.1	0.2	

- 2. Active power represents normal data communication. Standby power is when the device is enabled for operation but there is no LAN traffic (cable not connected). Power down current is the minimum power state used when not connected and mobile.
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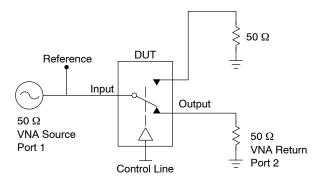


Figure 3. Bandwidth

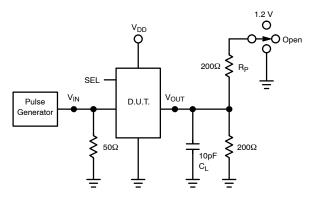


Figure 4. Three–State and  $t_{\text{pd}}$  Test Setup

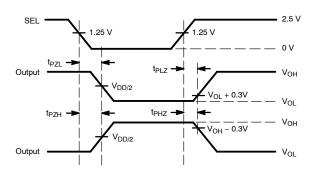


Figure 5. Three-State Timing Diagram

# **SWITCH POSITIONS**

Test	Switch
t <sub>PLZ</sub> , t <sub>PZL</sub> (Output on B-Side)	1.2 V
t <sub>PHZ</sub> , t <sub>PZH</sub> (Output on B-Side)	GND
t <sub>PD</sub>	OPEN

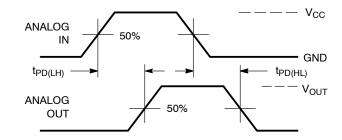


Figure 6. Propagation Delay

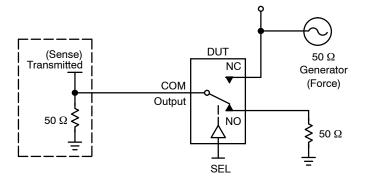
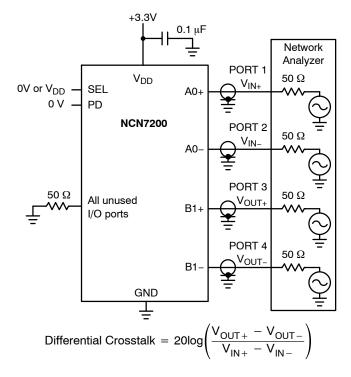


Figure 7. Off-Isolation



Measurements are standardized against shorts at IC terminals. Differential Crosstalk is measured between any two non-adjacent pairs.

Figure 8. Differential Crosstalk

# **APPLICATION INFORMATION**

# **Logic Inputs**

The logic control inputs can be driven up to +3.6 V regardless of the supply voltage. For example, given a +3.3 V supply, the output enables or select pins may be driven low to 0 V and high to 3.6 V: driving the control pins to the rails minimizes power consumption.

#### **Power-Supply Sequencing**

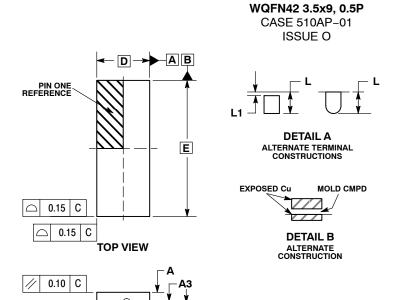
Proper power–supply sequencing is advised for all CMOS devices. It is recommended to always apply  $V_{DD}$  before applying signals to the input/output or control pins.

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NCN7200MTTWG	WQFN42 (Pb-Free)	2000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

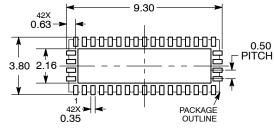


- DIMENSIONING AND TOLERANCING PER ASME
- CONTROLLING DIMENSION: MILLIMETERS.
  DIMENSION & APPLIES TO PLATED TERMINAL

  TO PLATE OF THE PETIMEN OF AND 0.30 M AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

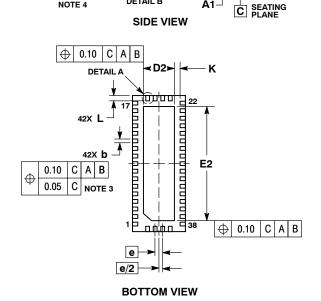
	MILLIN	MILLIMETERS				
DIM	MIN	MAX				
Α	0.70	0.80				
A1	0.00	0.05				
А3	0.20	REF				
b	0.20	0.30				
D	3.50	BSC				
D2	1.95	2.15				
E	9.00	BSC				
E2	7.45	7.65				
е	0.50	BSC				
K	0.20					
L	0.30	0.50				
L1	0.00	0.15				

#### **RECOMMENDED** MOUNTING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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DETAIL B

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NOTE 4

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